

ABSTRACT

METHOD OF MANUFACTURING ELECTRONIC CARDS

The present invention concerns a method of manufacturing complex electronic cards each including an electronic device or assembly (40) formed of a first electronic unit (4) at least partially arranged in a window in a solid bottom layer of the card and a second electronic unit (10),
5 incorporated in the body of the card, at least partially formed by a resin provided on the solid bottom layer. In order to prevent the resin from flowing into a slit between the lateral wall of the window and the second unit inserted therein, a protective film is arranged to cover the edge of the rear
10 face of the first unit and a zone peripheral to the aperture in the solid layer. According to the invention, the electronic device or assembly (40) is first formed and then placed on the bottom solid layer. The protective film is arranged between the two units after or when the electronic device or assembly is formed. Therefore according to the invention the protective film
15 is formed, for example, of several parts (24, 26) having respective profiles that define an aperture into which the electrical connection (18) between the two electronic units (4, 10) passes. In another embodiment, the protective film is formed of a single part having at least one slit starting from an aperture (32) made in said part and provided to allow the electrical
20 connection to pass therethrough. In another embodiment, the protective film has flaps at the edge of the aperture and is assembled to the solid bottom layer prior to addition of the electronic device or assembly.

Figure 2